L Number	Hits	Search Text	DB	Time stamp
1	1	("4383886").PN.	USPAT	2003/06/29
2	1	("4700467").PN.	USPAT	17:22 2003/06/29
3	60	wafer with (wafer and (joints or joint) and etch)	USPAT; US-PGPUB; EPO; JPO;	17:22 2003/06/29 17:24
4	40	(wafer with (wafer and (joints or joint) and etch)) and (@ad<20001102)	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/06/29 18:52
5	o	batch adj transfer adj wafer	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/06/29 17:32
6	2670	transfer adj wafer	IBM_TDB USPAT; US~PGPUB; EPO; JPO;	2003/06/29 17:32
7	2046	(transfer adj wafer) and (@ad<20001102)	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/06/29 20:02
8	709	((transfer adj wafer) and (@ad<20001102)) and (etch or etchant or etching)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/06/29 18:12
9	16444	(mems or microelectromechanical or actuator or mirror or mirrors or micromachining or ((opto or optical) near (device or devices))) and (etch or	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/06/29 18:49
10	10897	actuator or mirror or mirrors or micromachining or ((opto or optical) near (device or devices))) and (etch or etchant or etching) and wafer) and	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 19:04
11	8810	(@ad<20001102) (((mems or mirror or mirrors or micromachining or ((opto or optical) near (device or devices))) and (etch or etchant or etching) and wafer) and (@ad<20001102)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 18:20
12	1148	((((mems or microelectromechanical or actuator or mirror or mirrors or micromachining or ((opto or optical) near (device or devices))) and (etch or etchant or etching) and wafer) and (@ad<20001102)) and semiconductor) and	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 18:22
13	369	(bump or joint or joints or bumps) ((((mems or microelectromechanical or actuator or mirror or mirrors or micromachining or ((opto or optical) near (device or devices))) and (etch or etchant or etching) and wafer) and (@ad<20001102)) and semiconductor) and ((bump or joint or joints or bumps) with (wafer or semiconductor))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/29 18:22

14	531		**CDD##	12002/06/20
14	531	(((((mems or microelectromechanical or actuator or mirror or mirrors or	USPAT; US-PGPUB;	2003/06/29 18:39
	Ì	micromachining or ((opto or optical) near	EPO; JPO;	
		(device or devices))) and (etch or	DERWENT;	
		etchant or etching) and wafer) and	IBM_TDB	
	1	(@ad<20001102)) and semiconductor) and (bump or joint or joints or bumps)) and)	1
1	1	transfer	1	
15	201	(((((mems or microelectromechanical or	USPAT;	2003/06/29
		actuator or mirror or mirrors or	US-PGPUB;	18:39
ļ.	1	micromachining or ((opto or optical) near (device or devices))) and (etch or	EPO; JPO; DERWENT;	ļ
1	1	etchant or etching) and wafer) and	IBM TDB	i i
}	}	(@ad<20001102)) and semiconductor) and		ļ į
1	ĺ	((bump or joint or joints or bumps) with		
)	(wafer or semiconductor))) not (((((mems		
1	}	or microelectromechanical or actuator or mirror or mirrors or micromachining or		
1		((opto or optical) near (device or		
		devices))) and (etch or etchant or		į į
1	1	etching) and wafer) and (@ad<20001102))	1	
	1	and semiconductor) and (bump or joint or joints or bumps)) and transfer)		
16	133		USPAT;	2003/06/29
1		microelectromechanical or actuator or	US-PGPUB;	19:02
}		mirror or mirrors or micromachining or	EPO; JPO;	
Ì		((opto or optical) near (device or devices))) and (etch or etchant or	DERWENT;	
		(etching) and (wafer or substrate))	IBM_TDB	
17	94		USPAT;	2003/06/29
]		microelectromechanical or actuator or	US-PGPUB;	18:53
		mirror or mirrors or micromachining or	EPO; JPO;	
		((opto or optical) near (device or devices))) and (etch or etchant or	DERWENT; IBM TDB	
		etching) and (wafer or substrate))) and	TDM_TDB	
ĺ	ŀ	(@ad<20001102)		
18	11	5336634.URPN.	USPAT	2003/06/29
19	92	 438/459.ccls. and ((mems or	USPAT;	18:59 2003/06/29
	1	microelectromechanical or actuator or	US-PGPUB;	19:30
) .	mirror or mirrors or micromachining or	EPO; JPO;	
]	((opto or optical) near (device or	DERWENT;	
20	72	devices))) and soi) (438/459.ccls. and ((mems or	IBM_TDB USPAT;	2003/06/29
120	, 2	microelectromechanical or actuator or	US-PGPUB;	19:04
		mirror or mirrors or micromachining or	EPO; JPO;	
	1	((opto or optical) near (device or	DERWENT;	
21	0	<pre>devices))) and soi)) and (@ad<20001102) 6455398.URPN.</pre>	IBM_TDB USPAT	2003/06/29
		0100000. OREM.	OBENT	19:08
22	0	6455398.URPN.	USPAT	2003/06/29
			1	19:08
23	21	("5281834" "5346848" "5373184" "5386137" "5407856" "5472914"	USPAT	2003/06/29
	1	"5502316" "5503704" "5523602"	1	19:08
	["5557120" "5606186" "5728623"		
	!	"5728624" "5849627" "5858855"		
		"5966622" "6004867" "6030884"		
24	63	"6074892" "6153495" "6180496").PN. 438/458.ccls. and ((mems or	USPAT;	2003/06/29
		microelectromechanical or actuator or	US-PGPUB;	19:37
	1	mirror or mirrors or micromachining or	EPO; JPO;	}
}]]	((opto or optical) near (device or	DERWENT;	
	Il	devices))) and soi)	IBM TDB	

25	63	(438/458.ccls. and ((mems or	USPAT;	2003/06/29
		microelectromechanical or actuator or	US-PGPUB;	19:44
1	}	mirror or mirrors or micromachining or	EPO; JPO;	13.11
	ł	((opto or optical) near (device or	DERWENT;	j
1	j	devices))) and soi)) not (("5281834"	1	1
}	}	"5346848" "5373184" "5386137"	IBM_TDB	1
}	ì		ì	l
İ	j	"5407856" "5472914" "5502316"	Ì	ĺ
)	"5503704" "5523602" "5557120"]	!
	}	"5606186" "5728623" "5728624"	}	ļ
1	ĺ	"5849627" "5858855" "5966622"	l	(
	Į.	"6004867" "6030884" "6074892"	į	1
1	{	"6153495" "6180496").PN.)	(}
26	4	((438/458.ccls. and ((mems or	USPAT;	2003/06/29
		microelectromechanical or actuator or	US-PGPUB;	19:32
1	1	mirror or mirrors or micromachining or	EPO; JPO;	1 2 3 3 2
1	1	((opto or optical) near (device or	DERWENT;	i
1		devices))) and soi)) not (("5281834"		[
			IBM_TDB	Į.
j		"5346848" "5373184" "5386137"]	(
1	1	"5407856" "5472914" "5502316"	l	(
ì	1	"5503704" "5523602" "5557120"		
Į	1	"5606186" "5728623" "5728624"	ĺ	1
1	("5849627" "5858855" "5966622"	ĺ	}
1	}	"6004867" "6030884" "6074892"	}	}
1		"6153495" "6180496").PN.)) and ((ball	}	
1	}	or bump or joint) and (@ad<20001102))	}	
27	36		USPAT;	2003/06/29
} ~ ')	or joint) and (@ad<20001102)	US-PGPUB;	19:55
1	1	or joint, and (ead 20001102)	EPO; JPO;	19.55
Í	1		ł .	Į.
	1		DERWENT;	
		400 (450	IBM_TDB	
28	38		USPAT;	2003/06/29
Į	1	or joint) and (@ad<20001102)	US-PGPUB;	20:04
Į.	}		EPO; JPO;	
			DERWENT;	
	ì		IBM TDB	}
29	32	(438/459.ccls. and wafer and (ball or	USPĀT;	2003/06/29
	ì	bump or joint) and (@ad<20001102)) not	US-PGPUB;	19:44
1	j	(438/458.ccls. and wafer and (ball or	EPO; JPO;	
1	1	bump or joint) and (@ad<20001102))	DERWENT;	
1	Į.	lamp of joins, and (caa 20001102),	IBM TDB	
31	21	((438/459.ccls. and wafer and (ball or	USPAT;	2002/06/20
1 3 1	1 21	(, , , , , , , , , , , , , , , , , , ,		2003/06/29
1	Į.	bump or joint) and (@ad<20001102)) not	US-PGPUB;	20:01
1	1	(438/458.ccls. and wafer and (ball or	EPO; JPO;	
}		bump or joint) and (@ad<20001102))) and	DERWENT;	
		((etch or etching or etchant) with wafer)	IBM_TDB	!
32	1678	((etch or etching or etchant) with wafer)	USPAT;	2003/06/29
1	Ì	and indium	US-PGPUB;	20:01
1	1		EPO; JPO;	
Ì	!		DERWENT;	1
1	ļ		IBM TDB	
33	1207	(((etch or etching or etchant) with	USPAT;	2003/06/29
1	120,	wafer) and indium) and (@ad<20001102)	US-PGPUB;	20:02
1	1	"STOT, and Indian , and (ead\20001102)	EPO; JPO;	20.02
1	1			
			DERWENT;	1
1 24	1070		IBM_TDB	
34	1078	((((etch or etching or etchant) with	USPAT;	2003/06/29
1	j l	wafer) and indium) and (@ad<20001102))	US-PGPUB;	20:04
1	į l	and semiconductor	EPO; JPO;	
1	1		DERWENT;	1
1	l I		IBM TDB	1
35	192	((((etch or etching or etchant) with	USPAT;	2003/06/29
{		wafer) and indium) and (@ad<20001102))	US-PGPUB;	20:05
1		and semiconductor) and (ball or bump or	EPO; JPO;	
{	}	joint)	DERWENT;	!
(!	JOHNO		1
L	لـــــــــــــــــــــــــــــــــــــ		IBM_TDB	